



April 2000

QFET™

FQB46N15 / FQI46N15

150V N-Channel MOSFET

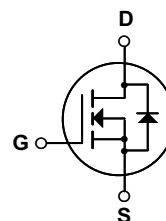
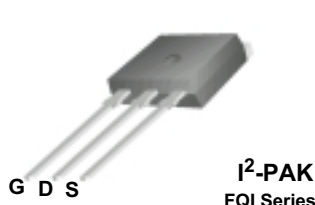
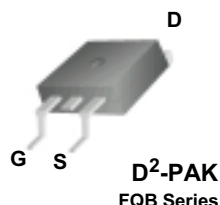
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifiers, high efficiency switching for DC/DC converters, and DC motor control, uninterrupted power supply.

Features

- 45.6A, 150V, $R_{DS(on)} = 0.042\Omega$ @ $V_{GS} = 10V$
- Low gate charge (typical 85 nC)
- Low C_{rss} (typical 100 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQB46N15 / FQI46N15	Units
V_{DSS}	Drain-Source Voltage	150	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	45.6	A
	- Continuous ($T_C = 100^\circ\text{C}$)	32.2	A
I_{DM}	Drain Current - Pulsed (Note 1)	182.4	A
V_{GSS}	Gate-Source Voltage	± 25	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	650	mJ
I_{AR}	Avalanche Current (Note 1)	45.6	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	21	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	6.0	V/ns
P_D	Power Dissipation ($T_A = 25^\circ\text{C}$) *	3.75	W
	Power Dissipation ($T_C = 25^\circ\text{C}$)	210	W
	- Derate above 25°C	1.43	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	0.7	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	--	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	$^\circ\text{C/W}$

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	150	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	--	0.16	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 150\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 120\text{ V}, T_C = 150^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 25\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 22.8\text{ A}$	--	0.033	0.042	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 22.8\text{ A}$ (Note 4)	--	33	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	2500	3250	pF
C_{oss}	Output Capacitance		--	520	670	pF
C_{rss}	Reverse Transfer Capacitance		--	100	130	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 75\text{ V}, I_D = 45.6\text{ A},$ $R_G = 25\text{ }\Omega$ (Note 4, 5)	--	35	80	ns
t_r	Turn-On Rise Time		--	320	650	ns
$t_{d(off)}$	Turn-Off Delay Time		--	210	430	ns
t_f	Turn-Off Fall Time		--	200	410	ns
Q_g	Total Gate Charge	$V_{DS} = 120\text{ V}, I_D = 45.6\text{ A},$ $V_{GS} = 10\text{ V}$ (Note 4, 5)	--	85	110	nC
Q_{gs}	Gate-Source Charge		--	15	--	nC
Q_{gd}	Gate-Drain Charge		--	41	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	45.6	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	182.4	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 45.6 A	--	--	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 45.6 A, dI _F / dt = 100 A/μs (Note 4)	--	130	--	ns
Q _{rr}	Reverse Recovery Charge		--	0.55	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 0.52\text{ mH}$, $I_{AS} = 45.6\text{ A}$, $V_{DD} = 25\text{ V}$, $R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 45.6\text{ A}$, $di/dt \leq 300\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

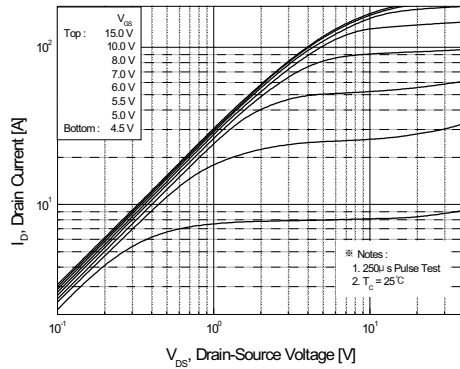


Figure 1. On-Region Characteristics

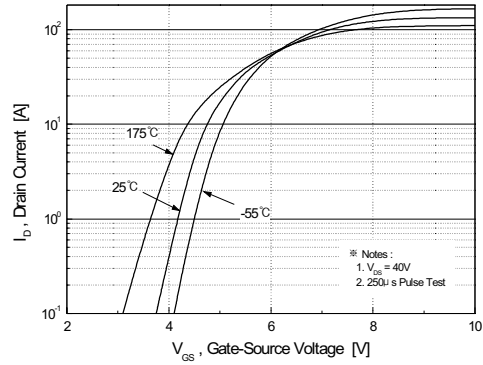


Figure 2. Transfer Characteristics

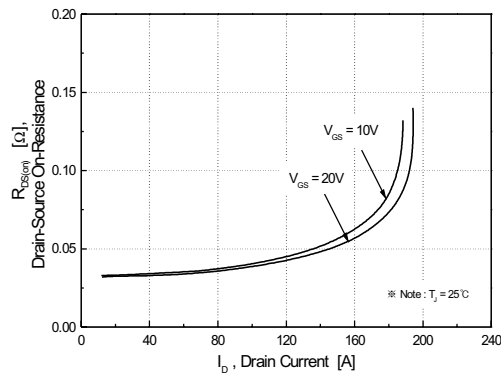


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

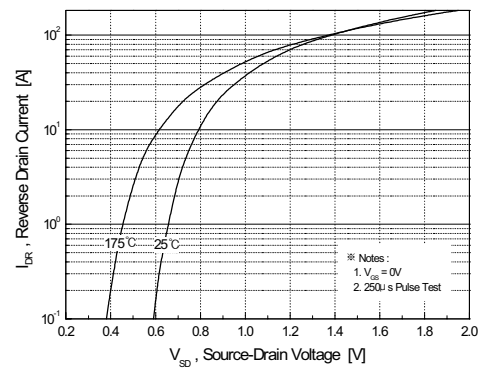


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

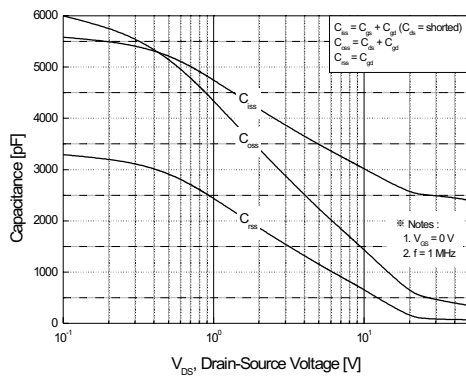


Figure 5. Capacitance Characteristics

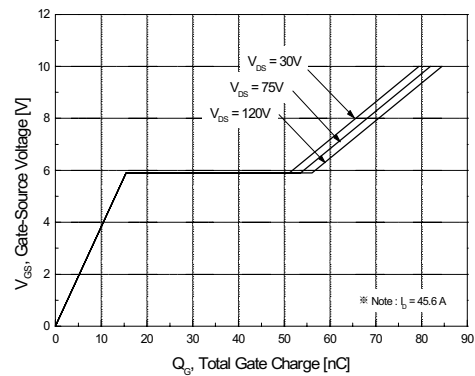


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

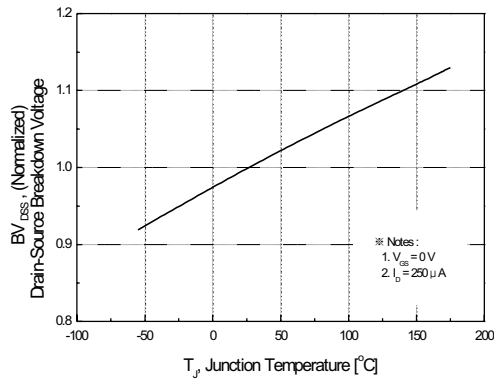


Figure 7. Breakdown Voltage Variation vs. Temperature

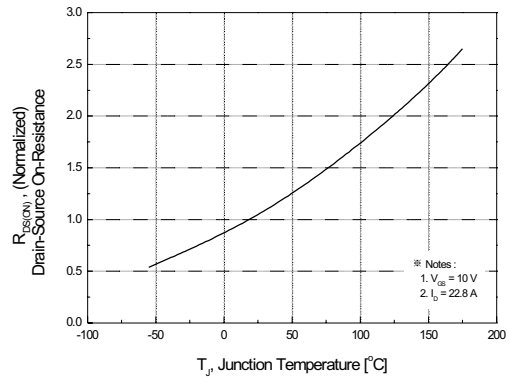


Figure 8. On-Resistance Variation vs. Temperature

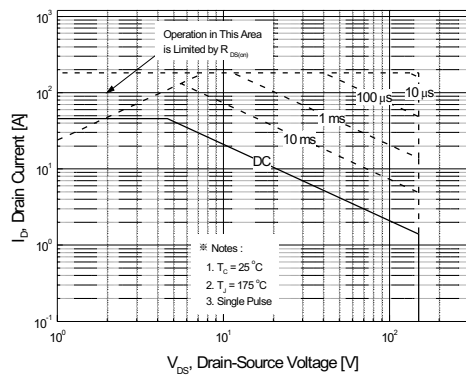


Figure 9. Maximum Safe Operating Area

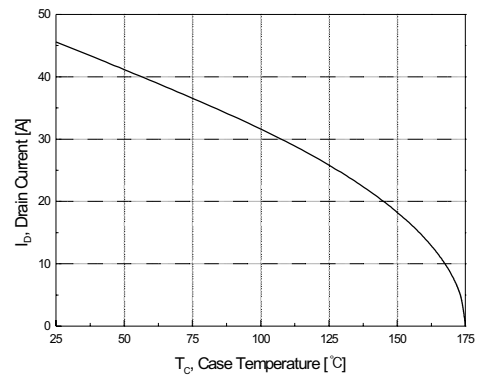


Figure 10. Maximum Drain Current vs. Case Temperature

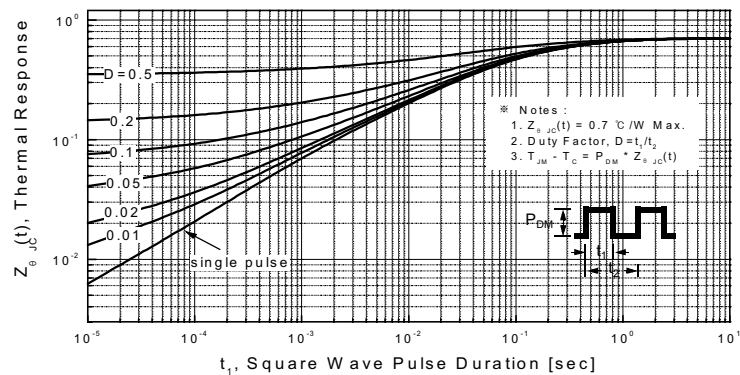
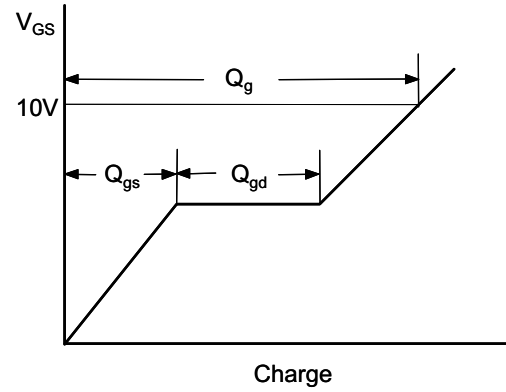
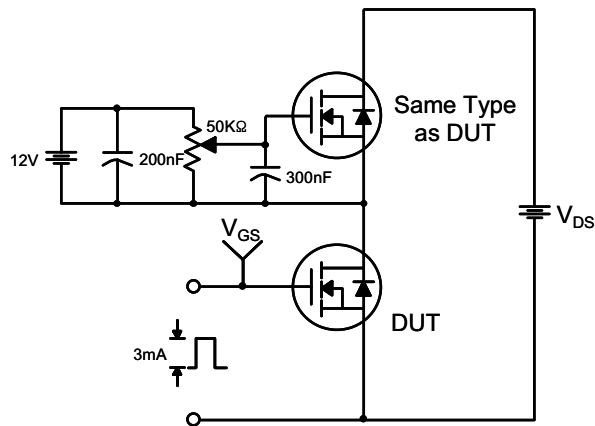
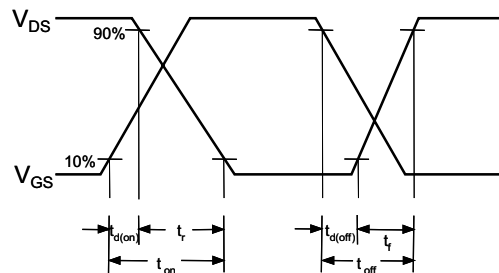
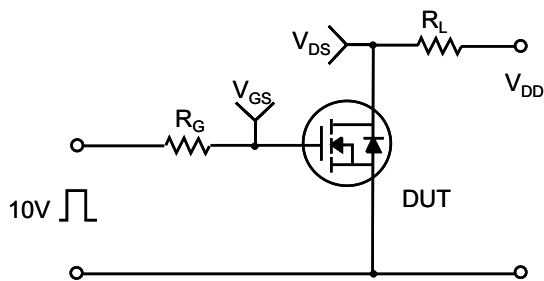


Figure 11. Transient Thermal Response Curve

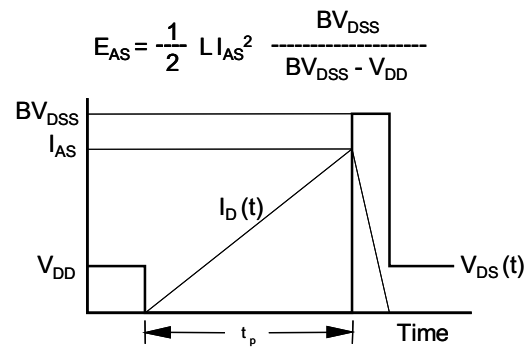
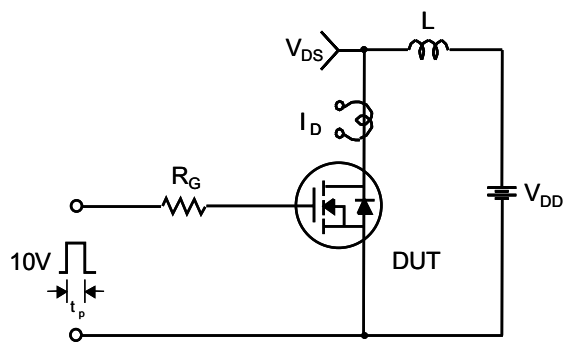
Gate Charge Test Circuit & Waveform



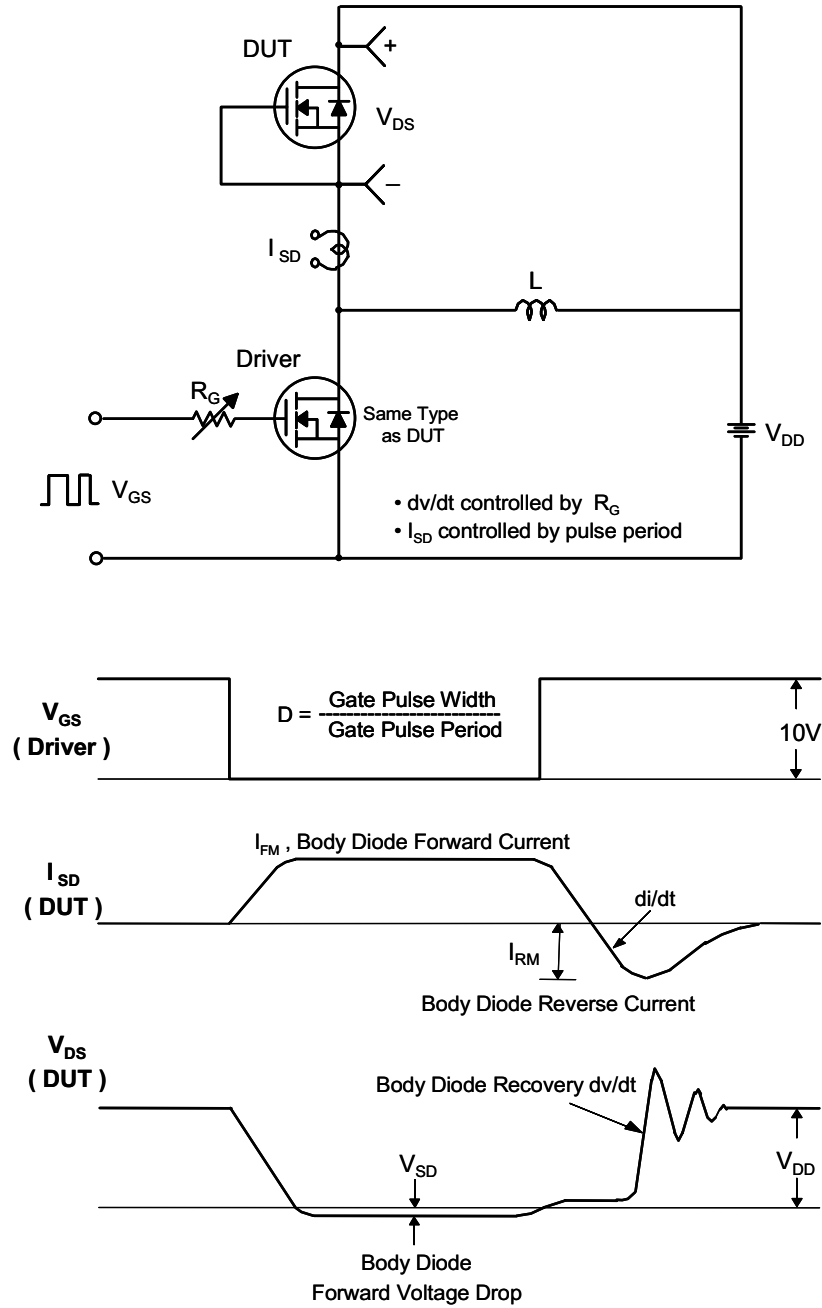
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



Technical drawing of a 10-pin D-sub connector showing front, side, and top views with dimensions in millimeters.

Front View (Top Left):

- Overall width: 9.90 ± 0.20
- Overall height: 15.30 ± 0.30
- Pin height: 1.40 ± 0.20
- Pin pitch: 2.54 TYP
- Pin diameter: 0.80 ± 0.10
- Internal width: 1.20 ± 0.20
- Internal height: 9.20 ± 0.20
- Bottom flange height: 4.90 ± 0.20

Side View (Top Right):

- Overall width: 4.50 ± 0.20
- Pin height: $1.30^{+0.10}_{-0.05}$
- Internal width: 0.10 ± 0.15
- Internal height: 2.00 ± 0.10
- Pin pitch: 2.54 ± 0.30
- Pin diameter: $0.50^{+0.10}_{-0.05}$
- Bottom flange height: 2.40 ± 0.20
- Internal width: 2.40 ± 0.20
- Internal height: 0.75
- Angle: $0^\circ \sim 3^\circ$

Top View (Bottom Left):

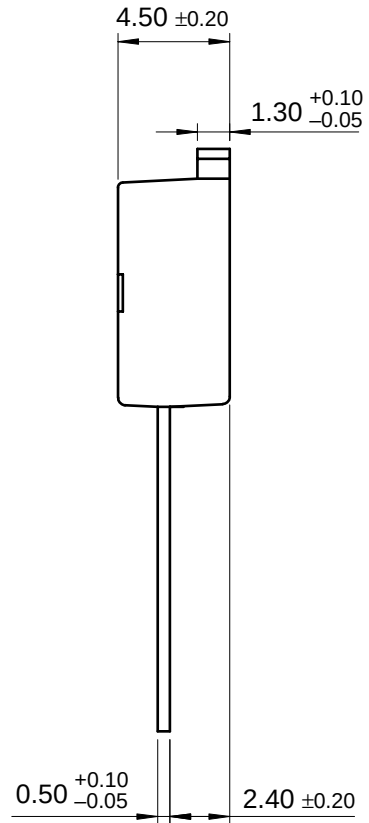
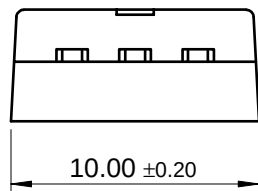
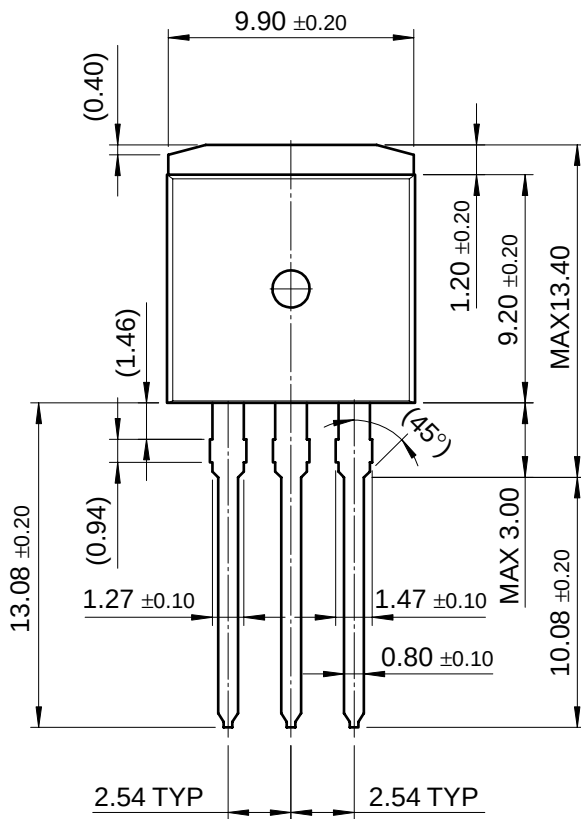
- Overall width: 10.00 ± 0.20

Top View (Bottom Right):

- Overall width: 10.00 ± 0.20
- Internal width: 8.00
- Internal width: 4.40
- Internal width: $(2XR0.45)$
- Overall height: 15.30 ± 0.30
- Internal height: 7.20
- Internal height: 9.20 ± 0.20
- Bottom flange height: 4.90 ± 0.20
- Pin pitch: 0.80 ± 0.10
- Internal height: (1.75)

Package Dimensions (Continued)

I²PAK



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